



Advanced LCP Substrates for HF & Microwave Applications

- Liquid Crystal Polymer (LCP) substrates with excellent high frequency properties
- Fine line patterning (down to 25 μ m)
- Precise cavity generation
- Application of heat sinks and lids
- DYCONEX is EN 9100 certified



Advanced LCP Substrates for HF & Microwave Applications



Liquid Crystal Polymer (LCP) is a superior organic multilayer material for RF applications with stable electrical and mechanical characteristics across a range of frequencies up to 100 GHz. Due to its very low water absorption, LCP properties remain nearly constant regardless of the presence of moisture, allowing its use for near-hermetic packages.

Metal plate

LCP Substrate with Heat Sink

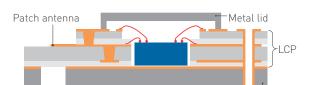
High power density application

Direct bonding to heat sink

Operating temperature up to 180°C

Gold wire bondable surface: ENEPIG

RF tracks covered by metal lid



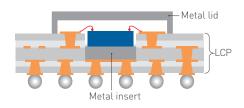
LCP BGA Package

Laser blind vias 50 or 75 µm

Lines / spaces: > 25 / 25 µm

Lid sealing for near-hermetic package

Heat dissipation via metal insert and thermal vias



LCP Base Material

Very flexible thermoplast

Excellent high frequency properties: ϵr = 2.9, $\tan \theta$ = 0.0025

High temperature stability: Tg > 280°C, Td > 320°C

Very low water absorption: < 0.04%

Low weight: 1.4 g / cm³

LCP Substrate Features

Directly bondable to a variety of materials to control CTE

Wire bondable cavity ledges to access inner layers without lossy vias

Air bridges

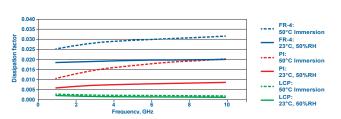
Thermal vias for heat dissipation

Application of heat sinks and metal lids

LCP HF Properties

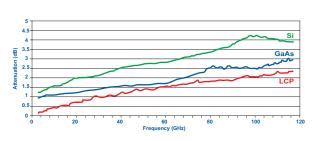
Dissipation factor variation with moisture

LCP, Polyimide (PI) and FR4 laminates



LCP HF Properties

Signal Attenuation



Based in Switzerland, DYCONEX has been in the PCB business for more than 50 years and delivers leading edge interconnect solutions in flex, rigid-flex and rigid technology. DYCONEX core competence lies in the production of highly complex HDI, high-frequency and high-reliability circuit boards for medical, defense, aerospace, industrial and semiconductor applications. DYCONEX is an MST company.





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www.mst.com

DYCONEX AG Grindelstrasse 40 CH-8303 Bassersdorf, Switzerland Phone +41 (43) 266 11 00 Fax +41 (43) 266 11 01 mail.dyconex@mst.com

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Micro Systems Technologies

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Micro Systems Technologies Management GmbH Sieversufer 7-9 DE-12359 Berlin, Germany Phone +49 (30) 68905-4001 info@mst.com www.mst.com